MLS™-G / HS1-VSP™ / HS2-VSP™ / SI-VSP™

高速訊號傳輸用電解銅箔

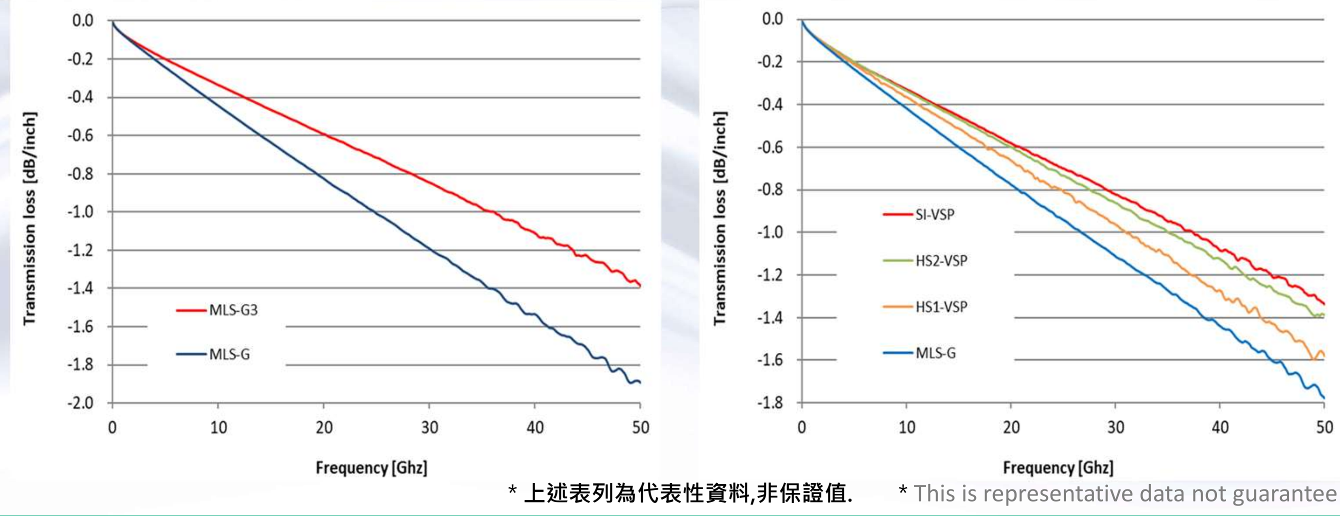
ED copper foil series for high speed data transmission

- **VSP®系列低粗糙度銅箔, 應用於Low Dk/Df板材, 更具低訊號損失特性.**
- VSP® copper foils with very low profile.
- Combined with low Dk/Df materials to show very low signal loss.
- **表面處理技術於 Low Dk/Df 膠系具優良的黏合特性.**
- Good bonding characteristics with low Dk/Df materials.

Product	Cross Section Image	Roughness B-side Rz	Thickness	Status
MLS™-G		3.5μm	1/2oz 1oz 2oz	Mass Production
MLS™-G3 **MLS™-G4**		1.5μm		
HS1-VSP™ **HS2-VSP™**	VSP™	1.5μm 1.0μm		
SI-VSP™	VSP™	0.6μm		

■ 高頻訊號損失比較 Signal Loss at high frequency (SI data)

Dielectric : Low loss Prepreg 136um, Dk 3.08, Df 0.0027
Cu thickness : 18 μ m　　Impedance : 50 Ω
Measurement mode : Microstrip Line / Single



* 上述表列為代表性資料,非保證值.　* This is representative data not guarantee